

### **CLAIM AMENDMENTS**

Please add new claims 21-27. No new matter is believed to be entered as a result of such new claims. The following listing of claims replaces all previous listings in this application.

1.       **(Original)**   A method for plating conductive paths of a printed circuit board, the method comprising:

          forming traces from at least one conductive path of a printed circuit board to an outer edge of the printed circuit board;

          connecting each trace to a plating bar such that the at least one conductive path of the printed circuit boards forms a single conductive path;

          plating the single conductive path; and

          routing the outer edge of the printed circuit board to electrically isolate each at least one conductive path.

2.       **(Original)**   A method as defined in claim 1, wherein forming traces from at least one conductive path of a printed circuit board to an outer edge of the printed circuit board further comprises forming traces on an internal layer of the printed circuit board.

3.       **(Original)**   A method as defined in claim 1, wherein forming traces from at least one conductive path of a printed circuit board to an outer edge of the printed circuit board further comprises forming traces on an external layer of the printed circuit board.

4.       **(Original)**   A method as defined in claim 1, wherein forming traces from at least one conductive path of a printed circuit board to an outer edge of the printed circuit board further comprises forming a trace from a particular conductive path to a via and forming a trace from the via to an outer edge of the printed circuit board.

5.       **(Original)**   A method as defined in claim 1, wherein forming traces from at least one conductive path of a printed circuit board to an outer edge of the printed circuit board further comprises forming a trace from a high speed transmission line to the outer edge.

6.       **(Original)**   A method as defined in claim 5, further comprising drilling a hole in the trace near the high speed transmission line.

7.       **(Original)**   A method as defined in claim 1, wherein plating the single conductive path further comprises plating high speed transmission lines.

8.       **(Original)**   A method as defined in claim 1, further comprising plating the single conductive path such that an area between contacts of the printed circuit board and a front edge of the printed circuit board does not include traces.

9.       **(Original)**   A method for plating a transmission line of a printed circuit board, the method comprising:

          forming a trace between a transmission line and an outer edge of a printed circuit board without forming a second trace between the transmission line and a front edge of the printed circuit board;

          applying an electrical signal to the transmission line through the trace to plate the transmission line; and

          drilling a hole through the trace near the transmission line to disconnect the transmission line from the trace.

10.      **(Original)**   A method as defined in claim 9, wherein forming a trace between a transmission line and an outer edge of a printed circuit board further comprises forming a trace between the transmission line and an existing conductive path.

11.      **(Original)**   A method as defined in claim 10, further comprising forming a trace between the existing conductive path and the outer edge of the printed circuit board.

12. **(Original)** A method as defined in claim 11, wherein forming a trace between a transmission line and an outer edge of a printed circuit board without forming a second trace between the transmission line and a front edge of the printed circuit board further comprises:

forming a first portion of the trace from the transmission line to a ground plane; and  
forming a second portion of the trace from the ground plane to another conductive path or to the outer edge of the printed circuit board.

13. **(Original)** A method as defined in claim 11, wherein forming a trace between a transmission line and an outer edge of a printed circuit board without forming a second trace between the transmission line and a front edge of the printed circuit board further comprises forming the trace on an internal layer of the printed circuit board.

14. **(Original)** A method as defined in claim 11, further comprising routing the printed circuit board to a final form factor to break a connection between the trace and a plating bar used to plate the transmission line.

15. **(Original)** A method for plating contact pads of a printed circuit board such that an area between a front edge of the printed circuit board and the contact pads does not include a trace, the method comprising:

forming a first trace from a first contact pad to an outer edge of a printed circuit board;  
forming a second trace from a second contact pad to the first contact pad or to a ground plane, wherein the second contact pad corresponds to a transmission line of the printed circuit board;  
connecting the first trace to a plating bar;  
applying a voltage to the plating bar such that the first contact pad and the second contact pad are plated;  
removing the plating bar; and  
drilling a hole through the second trace at a point near the second contact pad such that a stub of the second trace formed by drilling the hole does not impact characteristics of the transmission line.

16.       **(Original)**   A method as defined in claim 15, wherein forming a first trace from a first contact pad to an outer edge of a printed circuit board further comprises forming additional traces from additional contact pads to the outer edge of the printed circuit board.

17.       **(Original)**   A method as defined in claim 15, further comprising routing the printed circuit board to remove the plating bar such that the first contact is no longer electrically connected to the second contact.

18.       **(Original)**   A method as defined in claim 15, further comprising forming at least a portion of the first trace on an internal layer of the printed circuit board.

19.       **(Original)**   A method as defined in claim 15, further comprising forming at least a portion of the second trace on an internal layer of the printed circuit board.

20.       **(Original)**   A method as defined in claim 15, wherein drilling a hole through the second trace further comprises removing a long stub from being connected to the transmission line.

21. (New) A method for plating a selected portion of a printed circuit board, comprising:  
forming a first trace between a first conductive path and a via;  
forming a second trace between the via and a second conductive path so that the first and second conductive paths are electrically connected to each other by way of the via;  
connecting the first trace to a plating bar;  
applying a voltage to the plating bar such that the first conductive path and the second conductive path are plated;  
removing the plating bar; and  
drilling a hole through the second trace at a point proximate the second conductive path so that the second conductive path is electrically disconnected from the first conductive path.
22. (New) The method as recited in claim 21, wherein:  
the first conductive path comprises a contact; and  
the second conductive path comprises a transmission line.
23. (New) The method as recited in claim 21, wherein the first and second conductive paths are plated with gold.
24. (New) The method as recited in claim 21, wherein a portion of at least one of the traces is formed on an internal layer of the PCB.
25. (New) The method as recited in claim 21, wherein a portion of at least one of the traces is formed on an external layer of the PCB.
26. (New) The method as recited in claim 21, wherein a portion of at least one of the conductive paths is formed on an internal layer of the PCB.
27. (New) The method as recited in claim 21, wherein a portion of at least one of the conductive paths is formed on an external layer of the PCB.